



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Coyle, et al.

Docket No.: TI-31794

Serial No.: 09/992,387

Examiner: Lewis, M.

Filed: 11/16/01

Art Unit: 2822

For: FLIP-CHIP ON FILM ASSEMBLY FOR BALL GRID ARRAY PACKAGES

INFORMATION DISCLOSURE STATEMENT

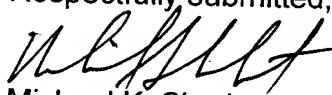
Assistant Commissioner for Patents
Washington, DC 20231

Dear Sir:

MAILED CERTIFICATE
I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231.

8-27-02
Date
Marianna Smith
Marianna Smith

Please make the references listed on the enclosed PTO-1449 of record under 37 C.F.R. 1.56, 1.97, and 1.98 in the patent application identified above. They were cited in a corresponding European patent application. Copies of the listed references and European search report are enclosed. Please charge the \$180.00 fee to Deposit Account No. 20-0668.

Respectfully submitted,

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